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January 2010

FDC642P

Single P-Channel 2.5V Specified PowerTrench® MOSFET -20 V, -4.0 A, 65 m Ω

Features

- Max $r_{DS(on)} = 65 \text{ m}\Omega$ at $V_{GS} = -4.5 \text{ V}$, $I_D = -4.0 \text{ A}$
- Max $r_{DS(on)}$ = 100 m Ω at V_{GS} = -2.5 V, I_D = -3.2 A
- Fast switching speed
- Low gate charge (11nC typical)
- High performance trench technology for extremely low r_{DS(on)}
- SuperSOTTM-6 package: small footprint (72% smaller than standard SO-8); low profile (1 mm thick)
- Termination is Lead-free and RoHS Compliant



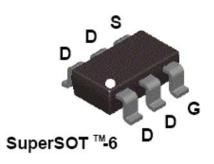
General Description

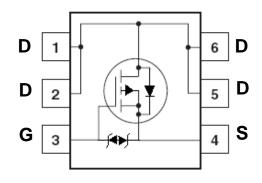
This P-Channel 2.5V specified MOSFET is produced using Fairchild's advanced PowerTrench® process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

These devices have been designed to offer exceptional power dissipation in a very small footprint for applications where the larger packages are impractical.

Applications

- Load switch
- Battery protection
- Power management





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			-20	V
V_{GS}	Gate to Source Voltage			±8	V
	-Continuous	T _A = 25°C	(Note 1a)	-4.0	۸
ID	-Pulsed			-20	Α
Б	Power Dissipation		(Note 1a)	1.6	14/
P_{D}	Power Dissipation		(Note 1b)	0.8	W
T _J , T _{STG}	Operating and Storage Junction Temperature	Range		-55 to + 150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.642	FDC642P	SSOT-6 TM	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	octeristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-13		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -16 V, V _{GS} = 0 V			-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.4	-0.6	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		2.5		mV/°C
		$V_{GS} = -4.5 \text{ V}, I_D = -4.0 \text{ A}$		45	65	
r	Static Drain to Source On Resistance	$V_{GS} = -2.5 \text{ V}, I_D = -3.2 \text{ A}$		55	100	mΩ
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -4.0 \text{ A},$ $T_J = 125^{\circ}\text{C}$		62	90	11152
9 _{FS}	Forward Transconductance	V _{DS} = -5 V, I _D = -4.0 A		15		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 10 V V 0 V	700	925	pF
Coss	Output Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$ - f = 1 MHz	110	150	рF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1411 12	95	145	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		6	12	ns
t _r	Rise Time	$V_{DD} = -10 \text{ V, } I_{D} = -1 \text{ A,}$	7	14	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = -4.5 V, R_{GEN} = 6 Ω	120	190	ns
t _f	Fall Time		52	83	ns
Q_g	Total Gate Charge	V 40.V I 4.A	11	16	nC
Q_{gs}	Gate to Source Charge	$V_{DD} = -10 \text{ V}, I_{D} = -4 \text{ A}$ $V_{GS} =4.5 \text{ V}$	1.1		nC
Q_{qd}	Gate to Drain "Miller" Charge	VGS4.5 V	3.0		nC

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain-Source Diode I	Forward Current			-1.3	Α
V_{SD}	Source-Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -1.3 \text{ A}$	(Note 2)	-0.7	-1.2	V

Notes

^{1:} R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.

a. 78 °C/W when mounted on a 1 in $^2\,\text{pad}$ of 2 oz copper.

b. 156°C/W when mounted on a minimum pad of 2 oz copper.

^{2:} Pulse Test: Pulse Width<300 us, Duty Cycle<2.0%.

Typical Characteristics T_J = 25°C unless otherwise noted

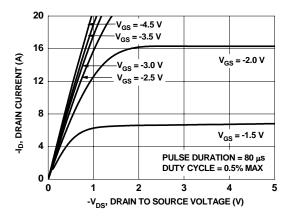
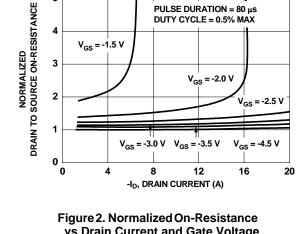


Figure 1. On Region Characteristics



PULSE DURATION = 80 µs

DUTY CYCLE = 0.5% MAX

vs Drain Current and Gate Voltage

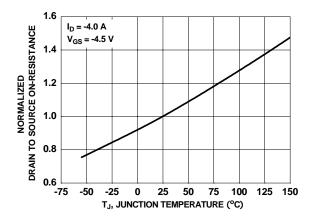


Figure 3. Normalized On Resistance vs Junction Temperature

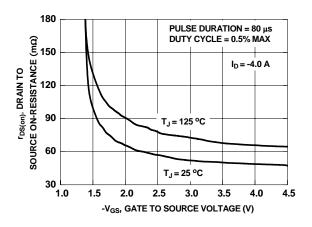


Figure 4. On-Resistance vs Gate to Source Voltage

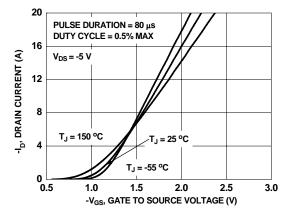


Figure 5. Transfer Characteristics

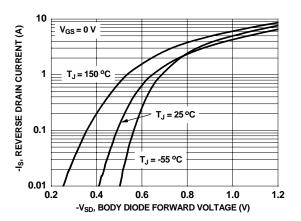


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

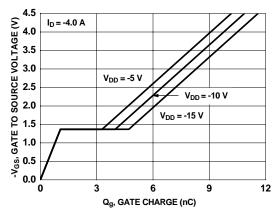


Figure 7. Gate Charge Characteristics

50

10

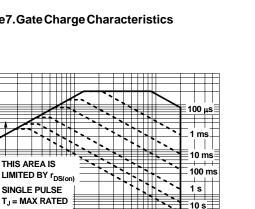
0.1

0.1

 $R_{\theta JA}$ = 156 °C/W

T_A = 25 °C

DRAIN CURRENT (A)



DC

60

10

Figure 9. Forward Bias Safe **Operating Area**

-V_{DS}, DRAIN to SOURCE VOLTAGE (V)

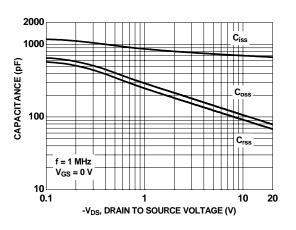


Figure 8. Capacitance vs Drain to Source Voltage

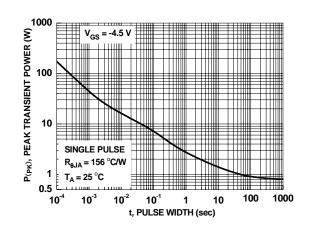


Figure 10. Single Pulse Maximum **Power Dissipation**

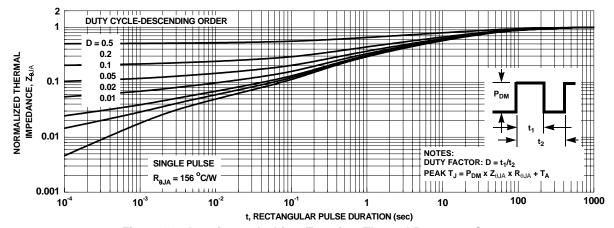


Figure 11. Junction-to-Ambient Transient Thermal Response Curve





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